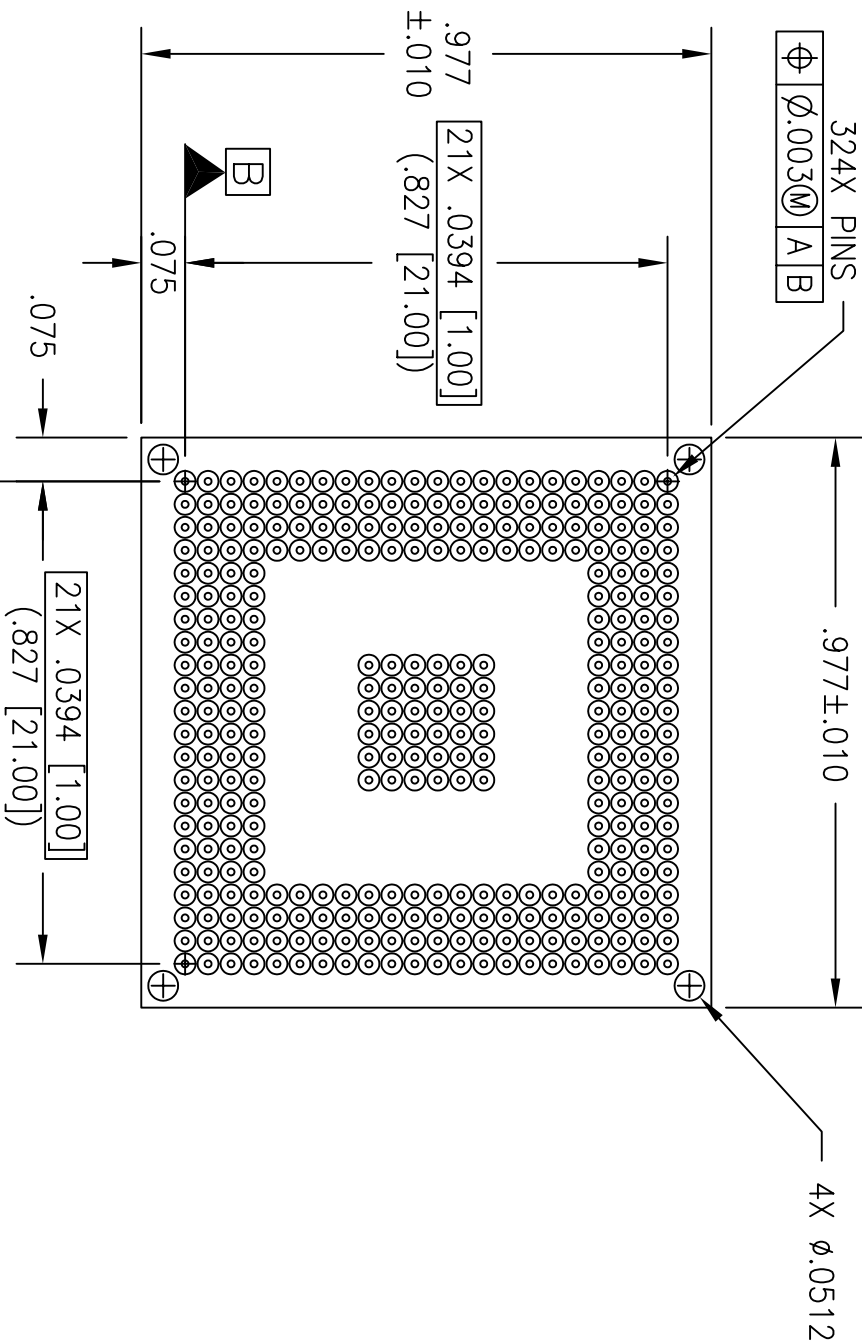
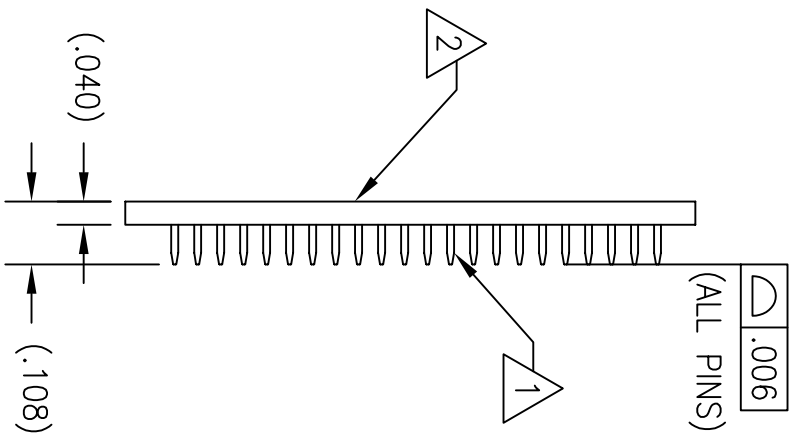


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TOP VIEW



RS VIEW



REV	DESCRIPTION	EGN	DATE	RELEASE
1	SALES RELEASE			

NOTES:

1. PINS  $\text{Ø.0117}$   
 MATERIAL: PHOSPHOR BRONZE.  
 PLATING: HARD GOLD OVER NICKEL.
2. INSULATOR MATERIAL: FR4.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES. TOLERANCES: ANGLES:  $\pm 1/64$  FRACTIONS:  $\pm .010$  DECIMALS:  $\pm .005$  .XXX  $\pm .0005$  .XXXX

CONTRACT NO.	DRAWN BY	DATE	TITLE	SIZE	SCALE	DRAWING NO.	REV
	DESIGNER	DATE	<b>INTERCONNECT SYSTEMS INC.</b> 708 VIA ALONDRA, CAMARILLO, CA 93012 HILo-BGA PIN BASE 22 X 22, 324 PINS 1mm PITCH	A	N/A	HLP-220324-B-10	1
	CHECKER	DATE		SWED AS: HLP-220324-B-10.DWG	FINISHED ASST: HLP-220324-B-10	SHEET 1 OF 1	

ASIZE

4

3

2

1